

PRESS RELEASE

During Productronica EIPC will be organising an IONMET/Prosurf joint dissemination seminar.

EIPC, one of the partners in both Framework 6 Projects, will be disseminating the work done, and the present state of play with regard to two exciting projects.

IONMET: a new plating technology by using ionic liquids and the effect on the PCB Industry.

IONMET is exploring the use of ionic liquid and deep eutectic solvents as electrolytes in a wide range of metal finishing processes of great importance to the surface finishing and printed circuit manufacturing sectors. This exciting new technology has the potential to significantly enhance the capability of SMEs in surface finishing and printed circuit manufacturing.

PROSURF:: a technology roadmap for PCB's.

PROSURF aims to support SMEs and other stakeholders in the printed circuit and surface finishing industries, by building the capability to innovate through greater involvement in Research and Development - the primary objective being to strengthen SME competitiveness in both the medium and long term. The project provides a range of free support services: a roadmap defining future research strategies, a best practice methodology to get SMEs involved in research and innovation, a partnering platform and more.

The Joint Seminar will be held on 14th November in Room B32 at Messe Munchen, commencing at 09.45am. **Participation is free**, and the seminar will be of specific interest to those who are involved with future technologies in the PCB industry.

Small and medium enterprises (SMEs) often do not have the resources to decide on the introduction of new technologies, one reason being the lack of knowledge about such new technologies or processes. The EU-sponsored Framework 6 has provided resources to help clarifying the usefulness of new chemicals and advanced existing or new processes for the industry.

As printed circuit boards (PCBs) are one of the key interconnect components, it is important for the industry to understand how these processes are developing over the next years. The seminar will show the future technological roadmap, as well as information about processes and new chemicals, and is therefore a vital tool in updating the electronics industry in Europe for a successful future. The seminar will help to provide a competitive advantage without conducting all research work in house.

The seminar on ProSurf and IONMET activities, taking place after nearly two years of project work, will help the manufacturing industry to refocus on successful technologies and processes. In addition, it will guide the fabricators to meet the challenging environmental requirements that have been established with RoHS and REACH.

Participants will learn how to adopt existing and new processes and chemicals to meet the future technical and environmental challenges in producing advanced PCBs.

The programme is fully given on our website www.eipc.org , but a summary is shown below.

IONMET:

9.45 - 10.00 The PCB Market with new challenges and opportunities.

Opening by Michael Weinhold, EIPC

10.00 - 10.15 Introduction of the IONMET framework Programme

By Khalid Shukri, Genacys Ltd., UK

10.15 - 11.00 Introduction to Ionic liquids

By Andrew Abbott, University Leicester, UK

11.00 - 11.30 An overview on Ionic liquids and how aluminium can be plated.

By Frank Endress, TU Clausthal-Zellerfeld, Germany

11.30 - 12.00 Will plating with Ionic liquids have an impact on PCB fabrication technology?

By Michael Weinhold, EIPC

12.00 - 12.30 Example: Electroless Silver Plating of PCB's

By Andrew Abbott, University Leicester, UK

12.30 - 13.30 Lunch (FREE OF CHARGE)**PROSURF:**

13.30 - 13.45 Introduction Prosurf

By Ian Dalrymple, C-Tech Innovation, UK

13.45 - 14.15 Prosurf website: a special support and services for SME

By Uwe Koenig, Deutsche Gesellschaft für Galvano -und
Oberflächentechnik

14.15 - 14.45 How to get successfully involved in EU R&D funding?

By Anthony Walker, RTC North, UK

14.45 - 15.30 Road map and technology developments including Material and
Process developments for PCB's

By Michael Weinhold, EIPC

15.30 - 16.00 Q&A